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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10061023	FILING DATE 01/30/2002	CLASS 275	SUBCLASS 257 675	GAU 2814	EXAMINER D. NGUYEN
**APPLICANTS: Chang Shyh-Ming; Jou Jwo-Huei; Lee Yu-Chi; Hu Dyi-Chung;					
**CONTINUING DATA VERIFIED: THIS APPLICATION IS A DIV OF 08/239,575 05/09/1994 PAT 5,427,382 * (*) Data inconsistent with PTO records.					
** FOREIGN APPLICATIONS VERIFIED:					
PG-PUB		DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>	
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials				ATTORNEY DOCKET NO ERSO83-002B	
TITLE : Composite bump bonding					

U.S. DEPT. OF COMM./PAT. & TM-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
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